

**Achieves high density and high accurate frequency by semi-additive process (SAP) using liquid crystal polymer (LCP) as a core material.**

## Product Characteristics

### Narrow pitch impedance control

Suitable for space-saving while suppressing signal reflection because wiring pitch is as narrow as 50μm or less and differential impedance of 100 ohm can be achieved.

### Narrow pitch IC mounting

Suitable for forming pad to mount narrow pitch IC etc. on FPC because pad can be formed correctly compared to conventional subtractive method.

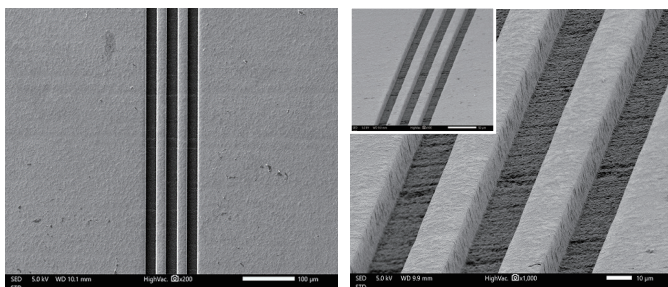
## Product Spec Example

- Number of layers : 2
- Connection Via :  $\phi 0.1\text{mm}$  through-Via
- Base material : Liquid crystal polymer (LCP) 50μm thickness
- Covercoat : Low dielectric coverlay, Solder resist etc.
- Conductor thickness : 20μm (reference)
- Line/Space : 20/20μm (reference)
- Impedance matching : Differential 100 ohm  $\pm 10\%$
- Surface treatment : ENEPIG (Wire bonding application)

## Product Photo Example

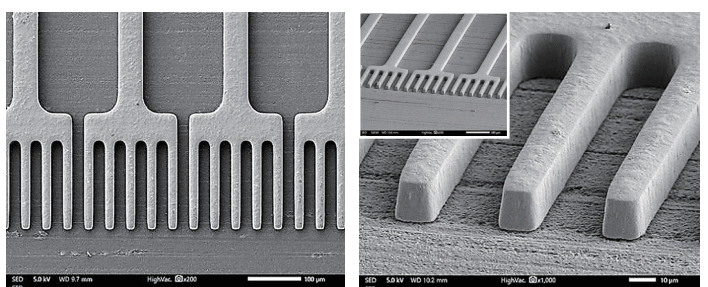
Narrow pitch differential line matched to 100 ohm

L/S 20/20μm



Mounting pad of narrow pitch component

L/S 20/20μm



Material provided by Toyo Kohan Co., Ltd.